



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814
Examiner: Dana FARAHANI

In Re PATENT APPLICATION Of:

Applicant(s): Yoshinori SHIZUNO

Serial No.: 09/705,729

Filed: November 6, 2000

For: SEMICONDUCTOR DEVICE AND METHOD
OF MANUFACTURING THE SAME

Docket No.: OKI-267

AMENDMENT
AFTER FINAL

January 7, 2003

Assistant Commissioner of
Patents and Trademarks
Washington, D.C. 20231

Sir:

In response to the Examiner's Action mailed on October 8, 2002, please amend
the above-identified application as follows:

IN THE CLAIMS:

Please amend the claims as follows:

1. (Twice Amended) A semiconductor device, comprising:
 - a semiconductor chip;
 - metal thin wires respectively connected to electrodes on said semiconductor chip;
 - a wiring board having an opening for accommodating said semiconductor chip and being electrically connected to said semiconductor chip by said metal thin wires;
 - a heat spreader having a flat principle surface, and having said semiconductor chip and said wiring board provided over the flat principal surface;

RECEIVED
JAN - 9 2003
TECHNOLOGY CENTER 2800

ENCLOSURE
FEE ENCLOSED: \$150.00
Pl as charg any further
fee to our Deposit Account
No. 18-0002